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(12) **United States Design Patent**  
**Umeda et al.**

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(54) **POWER MODULE DEVICE CONTAINING SEMICONDUCTOR ELEMENTS**

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(52) **U.S. Cl.**  
USPC ..... **D13/182**

(58) **Field of Classification Search**  
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H01L 25/18; H01L 23/4006; H01L  
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See application file for complete search history.

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(Continued)

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(57) **CLAIM**

The ornamental design for a power module device containing semiconductor elements, as shown and described.

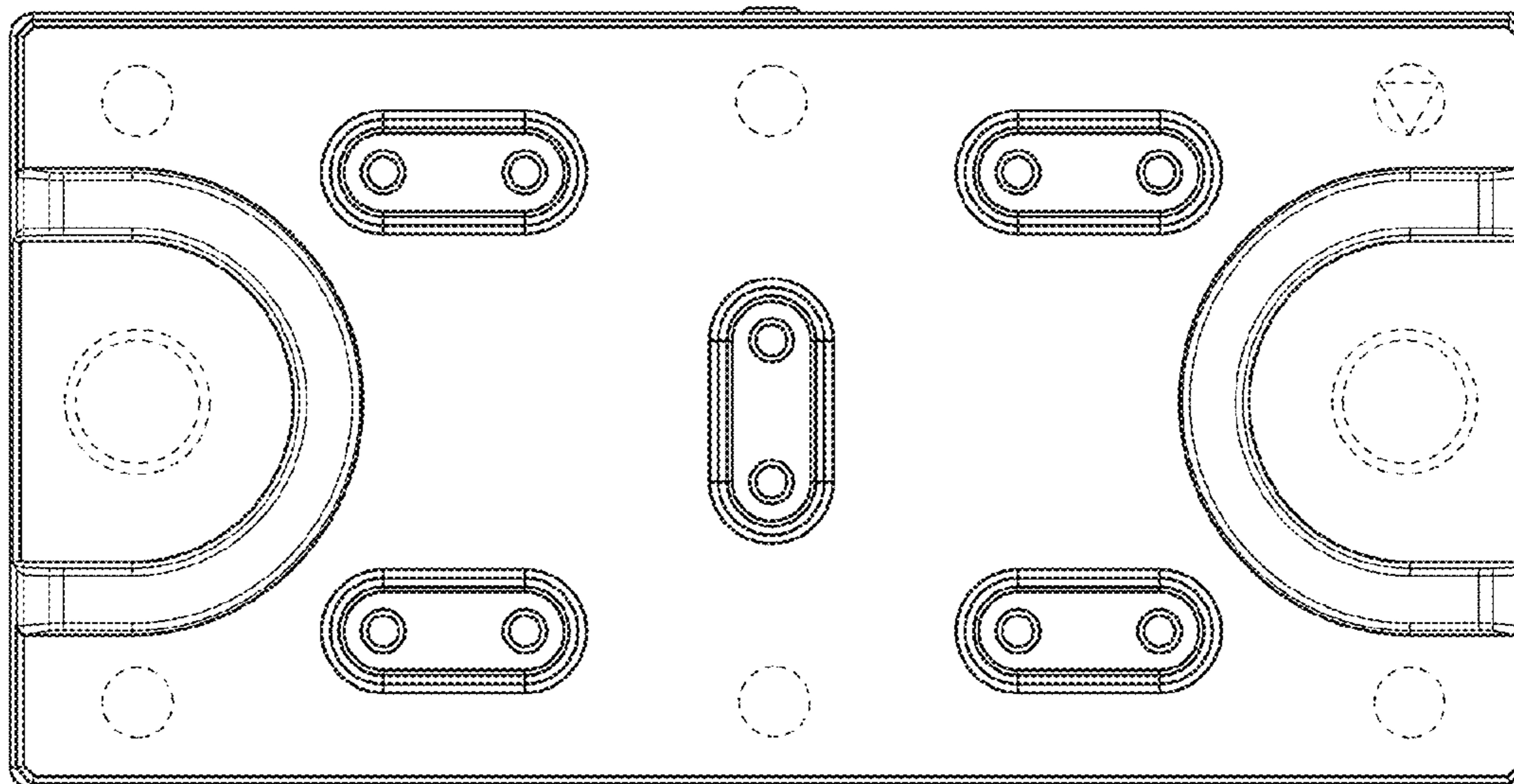
**DESCRIPTION**

- 1. Power module device containing semiconductor elements
- 1.1 : Front
- 1.2 : Back
- 1.3 : Top
- 1.4 : Bottom
- 1.5 : Right
- 1.6 : Left
- 1.7 : Perspective

The broken lines showing portions of the power module device containing semiconductor elements form no part of the claim.

This article is a power module device containing semiconductor elements; this product is used to control and/or supply electric power.

**1 Claim, 7 Drawing Sheets**



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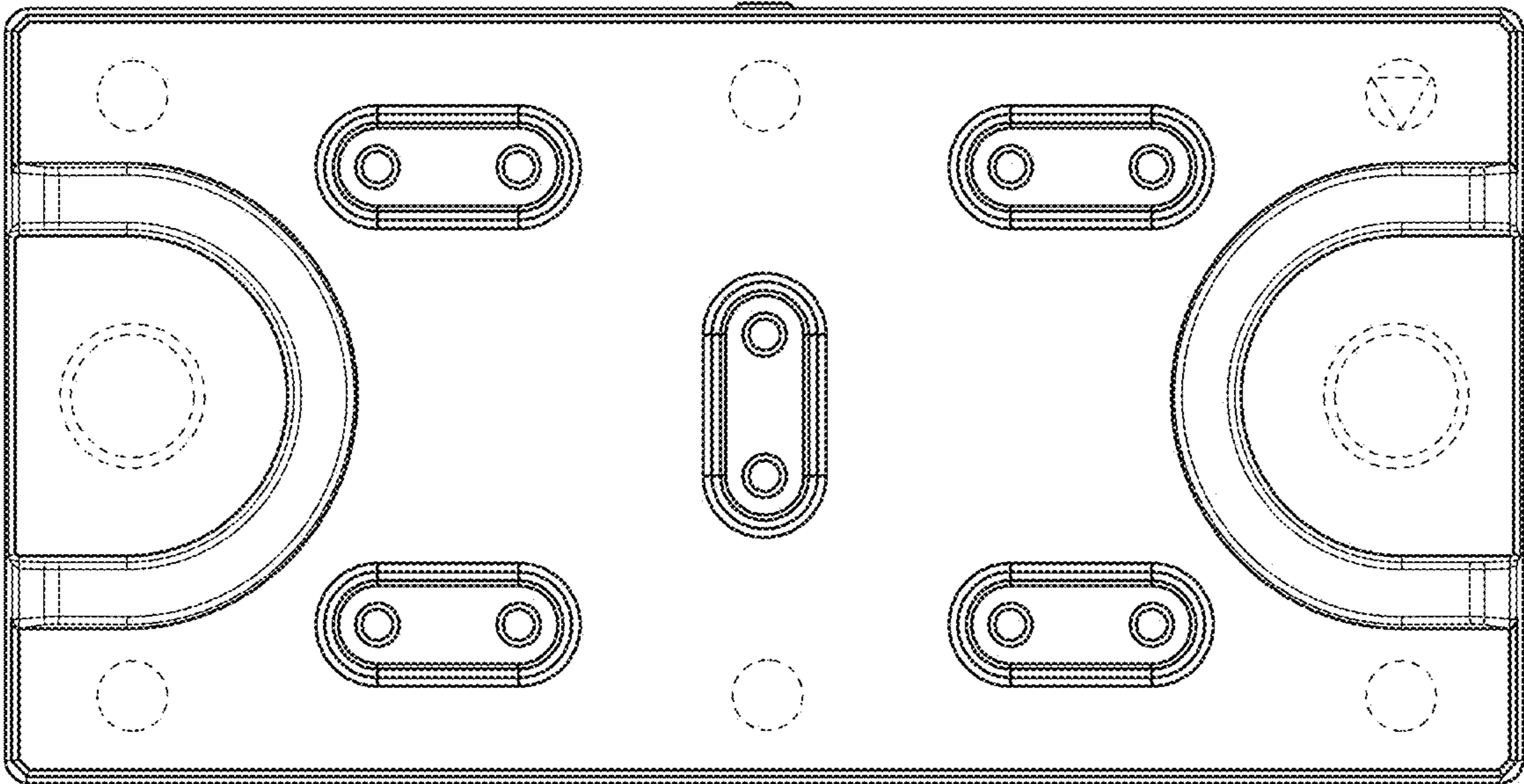


FIG. 1.1

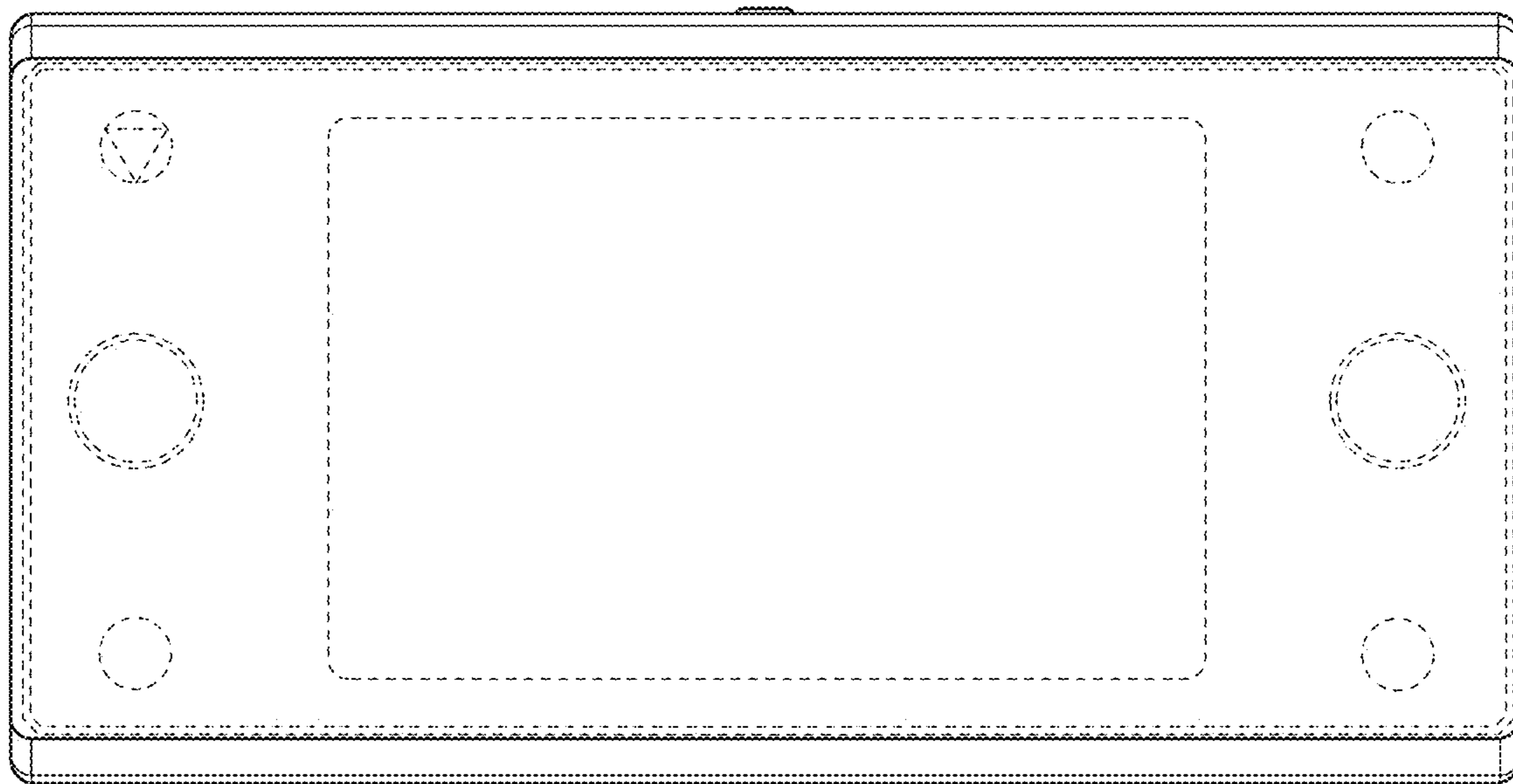
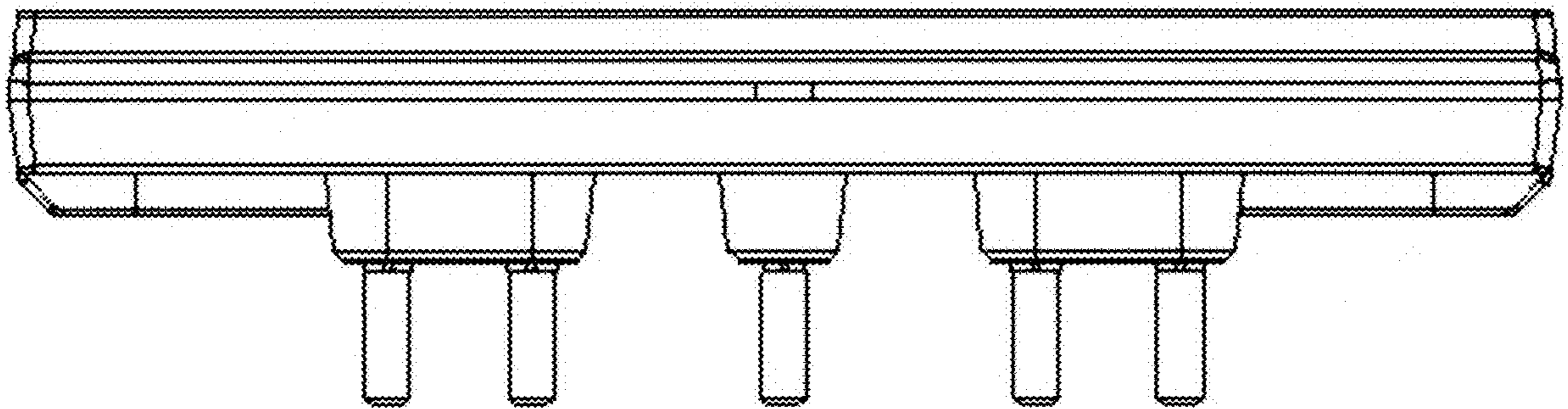


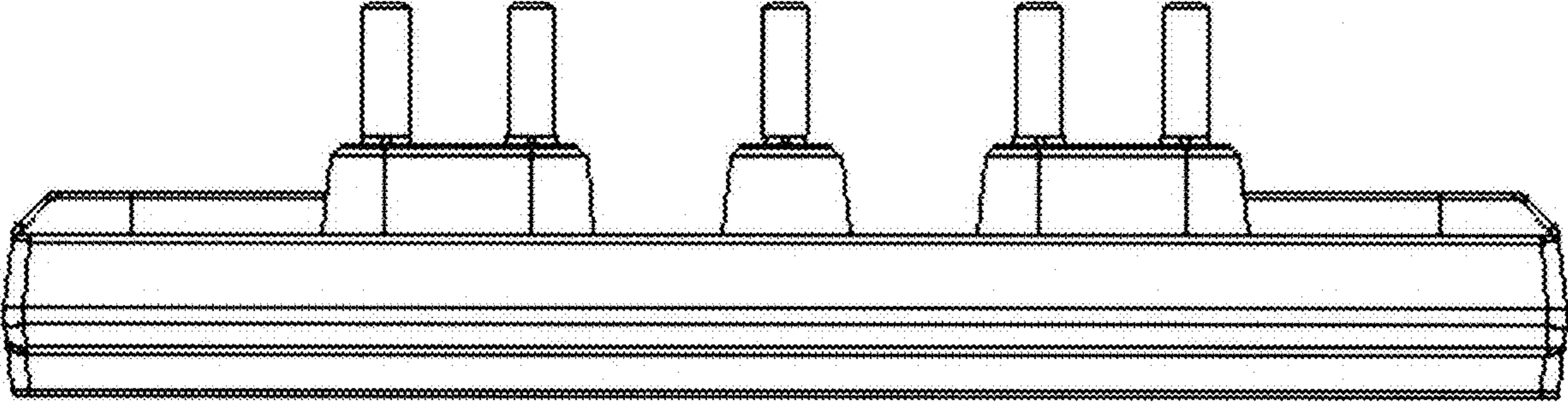
FIG. 1.2

1.3

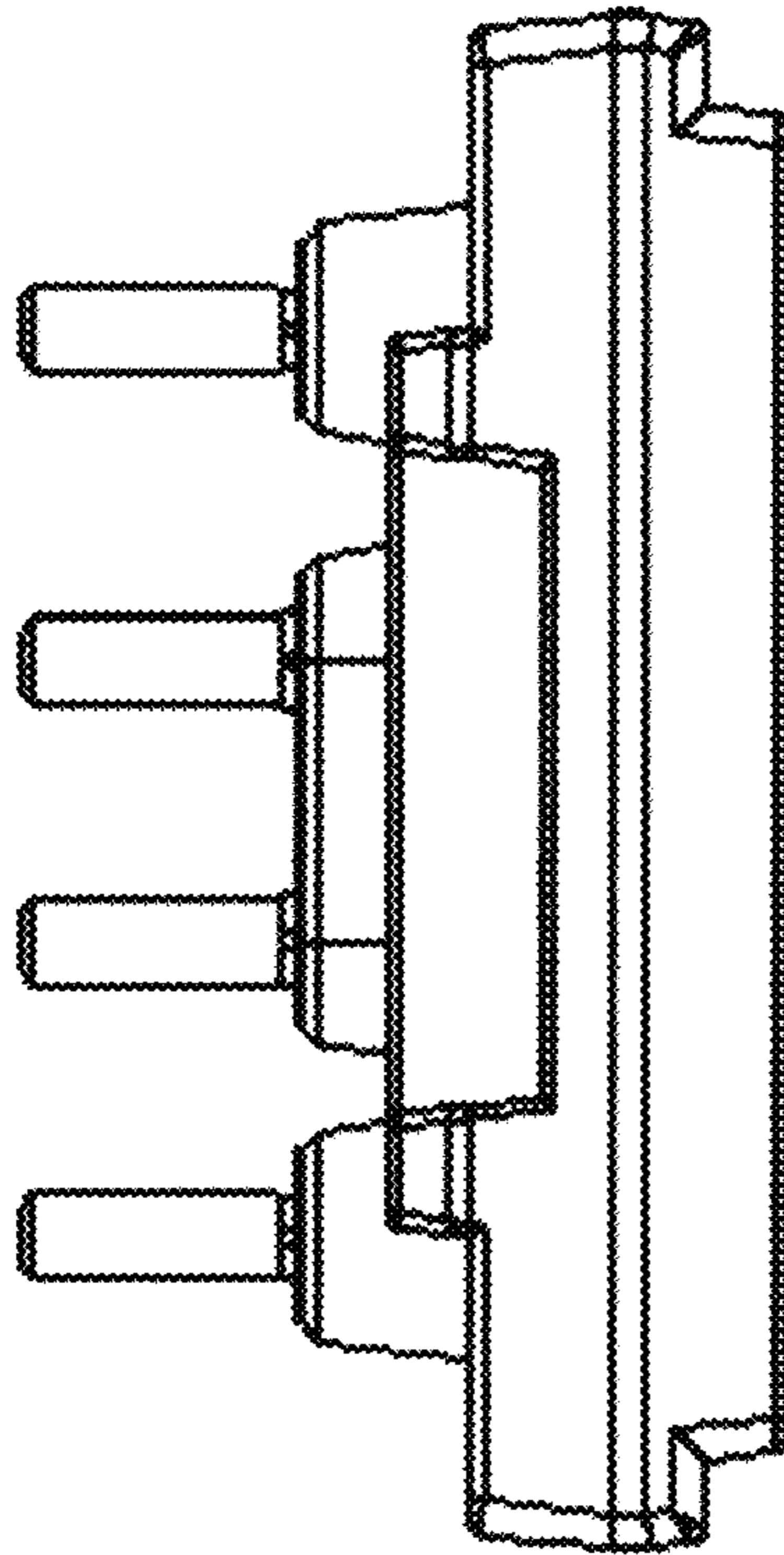




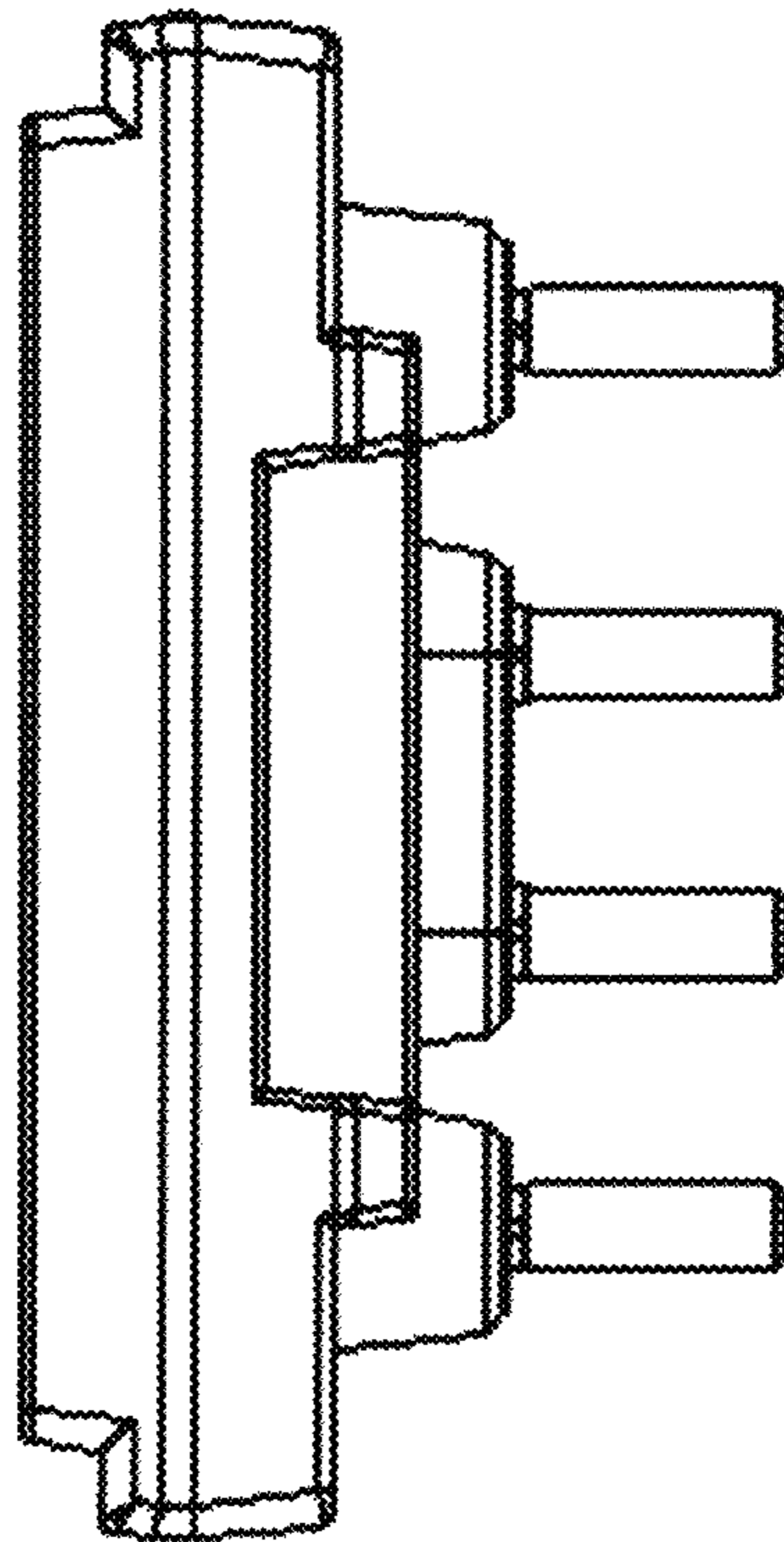
1.4



1.5



1.6





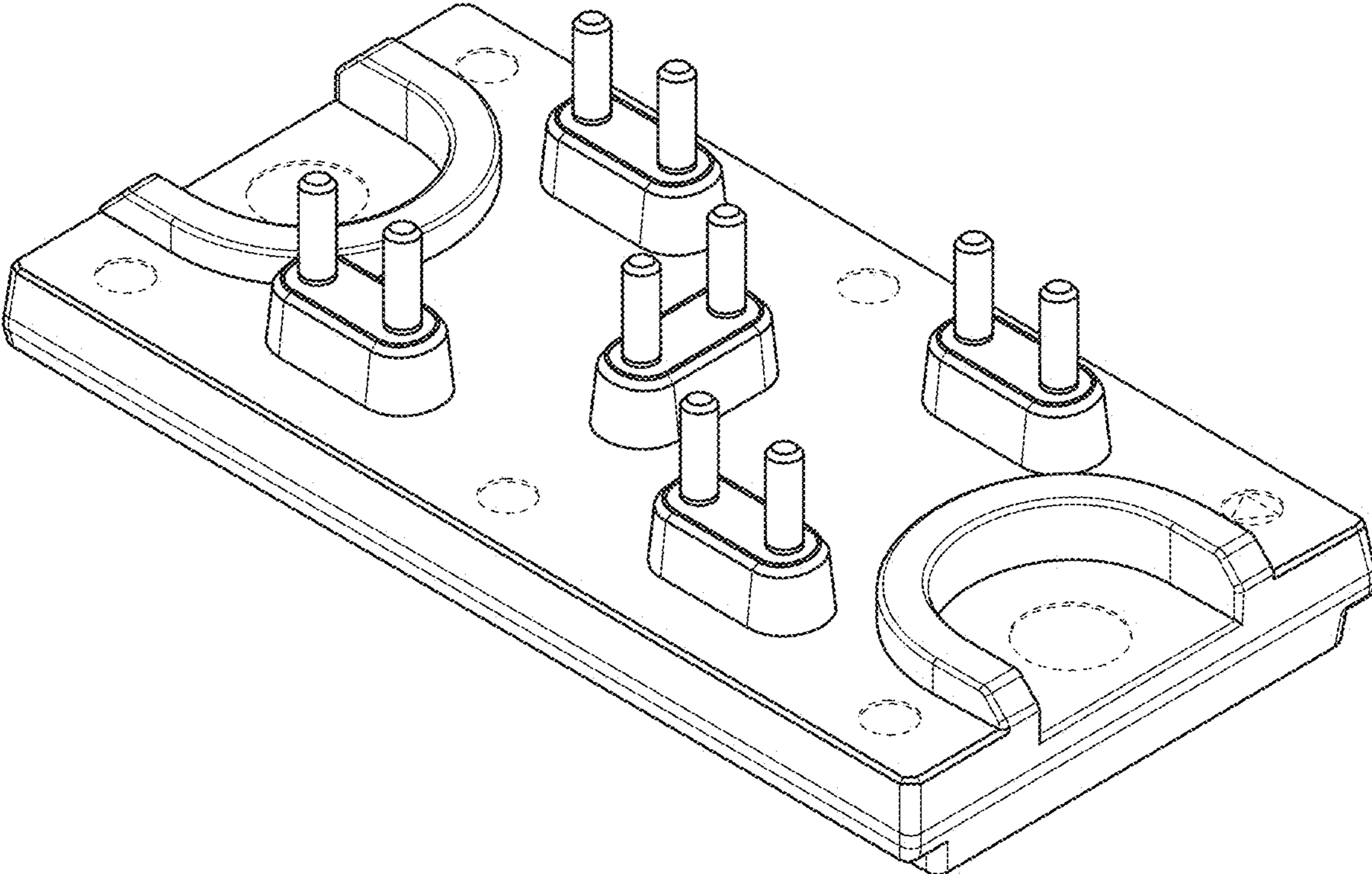


FIG. 1.7